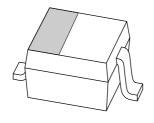
DISCRETE SEMICONDUCTORS

DATA SHEET



BAS416Low-leakage diode

Product specification Supersedes data of 2002 Nov 19 2004 Jan 26





Low-leakage diode

BAS416

FEATURES

- Plastic SMD package
- Low leakage current: typ. 3 pA
- Switching time: typ. 0.8 μs
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

APPLICATIONS

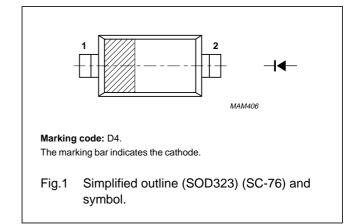
Low-leakage current applications in surface mounted circuits.

DESCRIPTION

Epitaxial, medium-speed switching diode with a low leakage current encapsulated in a small SOD323 SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE		PACKAGE				
NUMBER	NAME	DESCRIPTION	VERSION			
BAS416	_	plastic surface mounted package; 2 leads	SOD323			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		_	85	V
V_R	continuous reverse voltage		_	75	V
I _F	continuous forward current	see Fig.2	_	200	mA
I _{FRM}	repetitive peak forward current		_	500	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	4	Α
		t = 1 ms	_	1	Α
		t = 1 s	_	0.5	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

Note

1. Device mounted on an FR4 printed-circuit board.

Philips Semiconductors Product specification

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
		I _F = 1 mA	_	0.9	V
		I _F = 10 mA	_	1	V
		I _F = 50 mA	_	1.1	V
		I _F = 150 mA	_	1.25	V
I _R	reverse current	see Fig.5			
		V _R = 75 V	0.003	5	nA
		V _R = 75 V; T _j = 150 °C	3	80	nA
C _d	diode capacitance	V _R = 0; f = 1 MHz; see Fig.6	2	_	pF
t _{rr}	reverse recovery time	when switched from I _F = 10 mA to	0.8	3	μs
		$I_R = 10 \text{ mA}; R_L = 100 \Omega;$			
		measured at I _R = 1 mA; see Fig.7			

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	450	K/W

Note

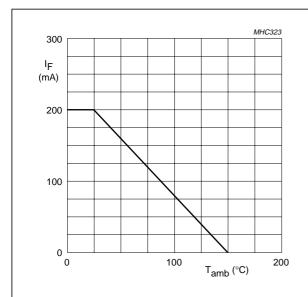
1. Refer to SOD323 (SC-76) standard mounting conditions.

Philips Semiconductors Product specification

Low-leakage diode

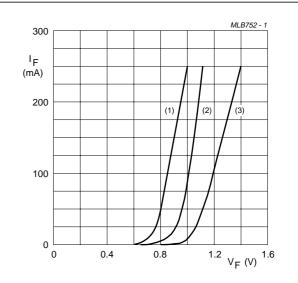
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GRAPHICAL DATA



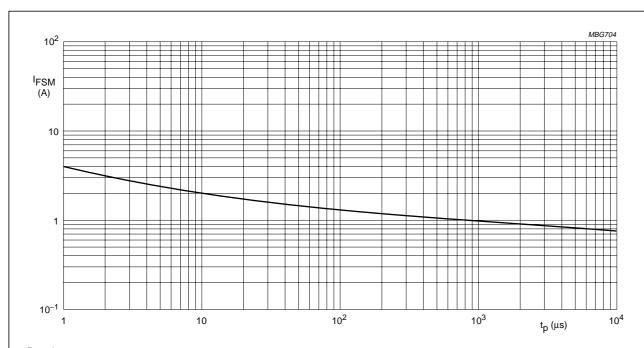
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_i = 150 \,^{\circ}\text{C}$; typical values.
- (2) $T_i = 25$ °C; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



Based on square wave currents.

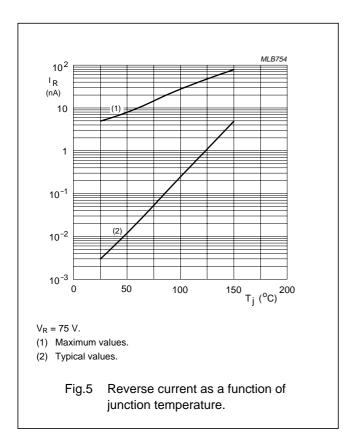
 T_j = 25 °C prior to surge.

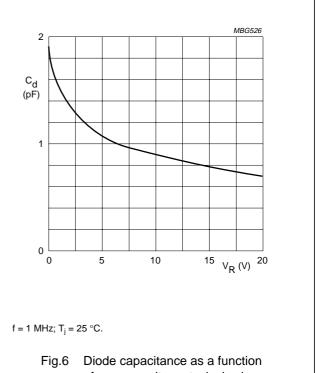
Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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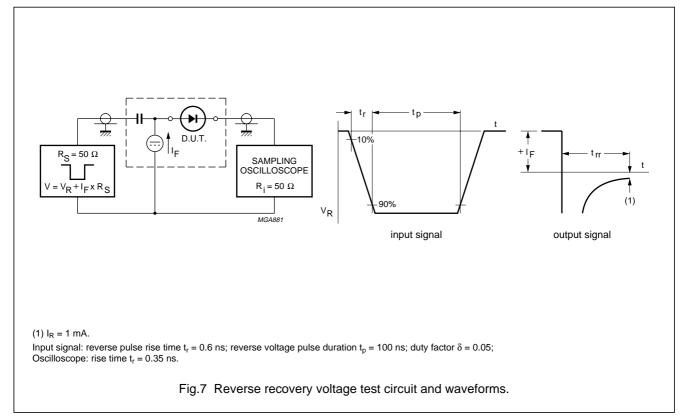
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of reverse voltage; typical values.



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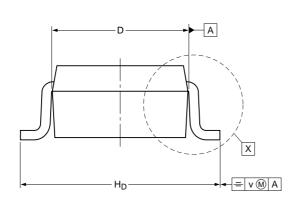
Low-leakage diode

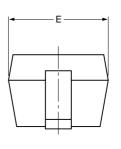
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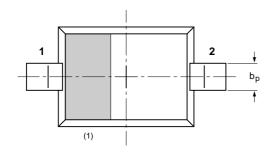
PACKAGE OUTLINE

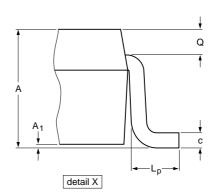
Plastic surface mounted package; 2 leads

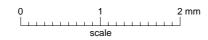
SOD323











DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE		REFERENCES				ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			99-09-13 03-12-17

Philips Semiconductors Product specification

Low-leakage diode

BAS416

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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